ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compo pyright 2005. IPC, Bannoc international and Pan-Amer	kburn, Illinois	. All rights reserv	tion with lower	level	parts, the	declarati	on encom	passes all low	ver level mate	erials for whi	if the item is an assembly ich the manufacturer has this declaration.			
1752-2 1.1	-	Web Site for Informat ://www.ipc.org/IPC-1		-1752 Standa	ard		m Type * tribute			eclaration Class * ass 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informa						
Supplier Information																
Company Name *	Company Unique ID	Unique ID Authority			Response Date *			esponse Doo	ument ID							
SEMTECH CORPORATION						2011-07-22										
Contact Name * ROYA READER	Title - Contact					Email - Contact * rreader@semtech.com			Duplicate Contact -> Authorized Representative							
Authorized Representati ROYA READER	Title - Representativ	e	Phone - Rep (805) 498-21	Email - Representative * rreader@semtech.com				Supplier Comments or URL for Additional Information								
Requester Item Number		Mfr Item Number		Mfr Item Name	Effecti	ive Date	Version Manuf		turing Site	Weight *	UOM	Unit Type				
	RClamp0522P.TCT			Ultra Low Capacitance TVS Arr			ra Ch				2.637	mg	Each			
Alternate Recommendation						Alternate Item C			nments							
Manufacturing Proces	ss In	formation														
Terminal Plating / Grid Array Material Terminal E			Base Alloy J-STD-020 MSL Ra			ating Peak Process Body Ter			ture Max Time	e at Peak Tem	perature Nur	nber of Reflow Cycles				
Nickel/Palladium/Gold (Ni/Pd/Au) CU Alloy Comments			,	1			26			30 se	econds 3					

Save the fields in this form to a file	Export Data	Import fields from a file into this form	Import Data	Clear all of the fields on this form	Reset Form	Lock the fields on this form to prevent chan	Look Cumption Fields					
RoHS Material Composition Declaration Declaration Declaration Type * Detailed												
		limit of 0.1% by mass (100 thers (PBDE) and quantity	, .				ominated Biphenyls (PBB),					
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2002/95/EC and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may not have relied on information. However, in situations where Supplier has not independently verified more that supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier renter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier stand the supplier's liability and the Company's remedies for issues that arise regarding information the Supplier is that arise rega												
RoHS Declaration	n * 1 - Item(s) does not contain	RoHS restricted substances per th	he definition above			Supplier Acceptance *	Accepted					
	declared item does not cont Il applicable exemptions.	ain RoHS restricted substanc	es per the definition a	bove except for defined	RoHS exemptions, then s	select the corresponding re	esponse in the RoHS Declaration					
Declaration Si	gnature											
		C 1 1 11 C (1 1)			· • • • • •	T 1: 10 11 1 4	D' i ll i					

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

Item/SubItem			Homogeneous	Weight	Unit of		Level	Substance Category			Substance	CAS	Exempt	Woight		Toleran	ce PPM
	Name		Material	weight	Measure		Lever	Substance Category			Substance	CAS	Exempt	weight	Measure	-	+
+I -I	Chip	+M -M	Doped Silicon	0.0799	mg	+C -	C Supplier		+S	-S	Silicon (Si)	7440-21-3		0.0799	mg		30,301
+I -I	Lead Frame	+M -M	C7025	0.9702	mg	+C -	C Supplier		+S	-S	Copper (Cu)	7440-50-8		0.9072	mg		344,02
									+S	-s	Silicon (Si)	7440-21-3		0.0069	mg		2,601
									+S	-s	Magnesium (Mg)	7439-95-4		0.0017	mg		628
						+C -	Св	Nickel (external applic	+S	-s	Nickel	7440-02-0		0.0303	mg		11,479
+1 -1	Lead Finish	+M -M	Ni/Pd/Au plating	0.0349	mg	+C -	Св	Nickel (external applic	+S	-s	Nickel	7440-02-0		0.0219	mg		8,294
						+C -	C Supplier		+S	-S	Palladium (Pd)	7440-05-3		0.002	mg		754
									+S	-s	Gold (Au)	7440-57-5		0.0004	mg		150
+1 -1	Bonding Wire	+M -M	Gold Wire	0.0119	mg	+C -	C Supplier		+S	-S	Gold (Au)	7440-57-5		0.0119	mg		4,512
+1 -1	Molding Compound	+М -М	EME-G770HCD	1.5367	mg	+C -	C Supplier		+S	-S	Silica Fused	60676-86-0		1.4368	mg		544,89
			-						+S	-s	Epoxy Resin	Proprietary		0.0461	mg		17,483
									+S	-s	Phenol Resin	Proprietary		0.0461	mg		17,483
									+S	-s	Carbon Black	1333-86-4		0.0077	mg		2,914
+1 -1	Die Attached Epoxy	+м -м	QMI519	0.0383	mg	+C -	C Supplier		+S	-s	Silver (Ag)	7440-22-4		0.0306	mg		11,586
			-						+S	-s	Palladium Compound	Proprietary		0.0001	mg		22
									+S	-s	2,6-di-tert-butyl-p-creso	128-37-0		0.000001	mg		1
									+S	-s	Hydroquinone	123-31-9		0.00000	mg		0
									+S	-S	Acrylate	Proprietary		0.0061	mg		2,295
									+S	-s	Bismaleimide Resin	Proprieatry		0.0011	mg		434
									+S	-s	Polymer of Polybutadie	Proprietary		0.0004	mg		145